PLATING PROCESS	pH	TEMP °F	POLYPROPYLENE							POLYESTER						
			MEDIA # - MICRON							MEDIA # - MICRON						
			402	405	407	410	415	425	430	502	505	507	510	515	525	530
			1-2	3-4	4-5	5-6	7-9	12-14	20-25	1-2	3-4	4-5	5-6	7-9	12-14	20-25
ANODIZING	1	60-90									X	X	X	X		
ANODIZING NI SEAL	5-5	200									X	X	X	X		
BRASS, BRONZE	10	100-200		X	X	X	X				X	X	X	X		
CADMIUM	12	100		X	X	X	X	X	X							
CROMIUM HEXAVALENT	1	110-130									X	X	X	X		
CROMIUM TRIVALENT	2	75									X	X	X	X		
COPPER ACID	1	20-120									X	X	X			
COPPER CYANIDE	11-13	120		X	X	X	X									
COPPER ELECTROLESS	14	100-140	X	X	X	X										
COPPER FLUOBORATE	1	70-85									X	X	X	X		
COPPER PYROPHOSPHATE	8-9	110-130									X	X	X	X		
LEAD FLUOBORATE	1	100									X	X	X	X		
NICKEL BRIGHT	3-5	125-150									X	X	X	X	X	X
NICKEL SEMIBRIGHT	2-5	130									X	X	X	X	X	X
NICKEL CHRLORIDE	2	120-150									X	X	X	X	X	X
NICKEL ELECTROLESS	4-11	100-200	X	X	X	X				X	X	X	X			
NICKEL SULFAMATE	3-5	100-140									X	X	X	X		
NICKEL WATTS	4	120-160									X	X	X	X		
NICKEL - IRON	3-4	135									X	X	X	X	X	X
IRON CHLORIDE	1	195									X	X	X	X	X	X
SILVER CYANIDE	12	70-120		X	X	X	X									
SILVER ACID	3-5	80-125									X	X	X	X		
TIN ACID	0.5	70									X	X	X	X		
TIN ALKALINE	12	140-180		X	X	X	X									
TIN-LEAD (SOLDER)	0.5	100									X	X	X	X		
TIN-NICKEL	2-5	150									X	X	X	X		
ZINC ACID	3-5	70-140									X	X	X	X	X	X
ZINC ALKALINE	14	75-100			X	X	X	X	X							
ZINC CYANIDE	14	79-50			X	X	X	X	X							